

SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520EJ/YD5V Yellow

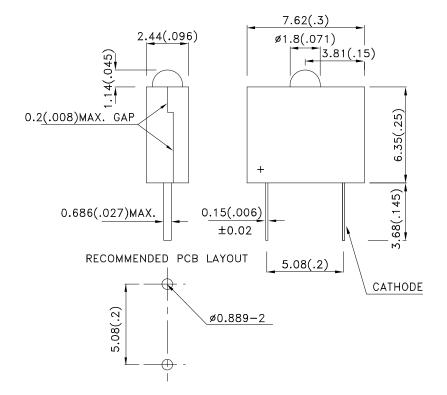
Features

- Black case enhances contrast.
- Vibration and shock resistant.
- 5V internal resistor.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.

 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.





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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] V= 5V		Viewing Angle [1]
		2.	Min.	Тур.	201/2
AM2520EJ/YD5V	Yellow (GaAsP/GaP)	Yellow Diffused	1.2	5	40°

- Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	V _F =5V
λD [1]	Dominant Wavelength	Yellow	588		nm	V _F =5V
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	V _F =5V
lF	Forward Current	Yellow	13	17.5	mA	V _F =5V
lR	Reverse Current	Yellow		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

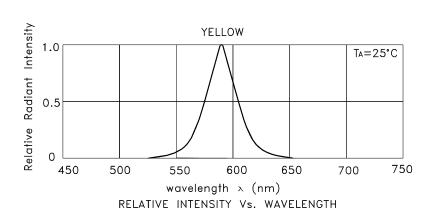
Parameter	Yellow	Units	
Power dissipation	85	mW	
Forward Voltage	6	V	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +70°C		
Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [1]	260°C For 3 Seconds		
Lead Solder Temperature [2]	260°C For 5 Seconds		

Notes:

- 2mm below package base.
 5mm below package base.

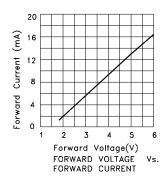
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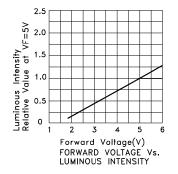
Note: 1.Wavelength: +/-1nm.

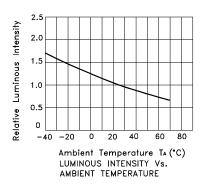


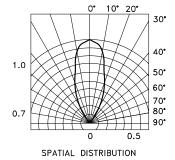
Yellow

AM2520EJ/YD5V

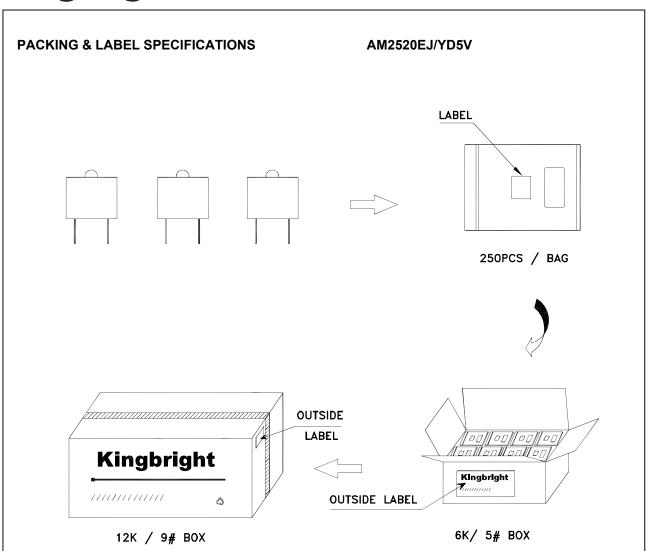


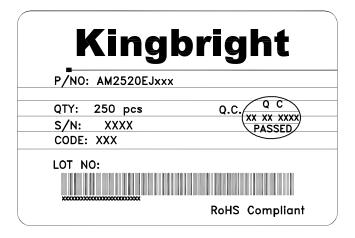






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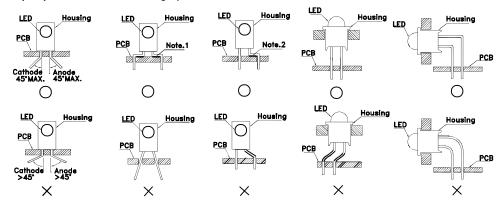




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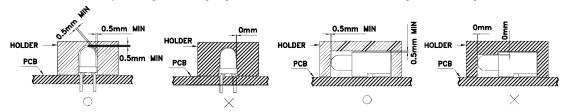
PRECAUTIONS

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

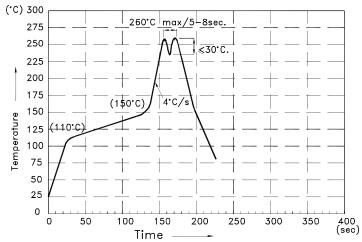


"() " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profile for Kingbright Thru—Hole Products



NOTES:

- 1.Recommend the wave temperature 245°C $\sim\!260^{\circ}\text{C}.$ The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

5.No more than once.

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